

Material Composition Specification

SOT-28 Case



Device average mass 15.9 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	4.4%	0.7	Si	7440-21-3	4.4%	0.7	43,986
bond wire	gold	1.07%	0.17	Au	7440-57-5	1.07%	0.17	10,682
leadframe	Cu alloy w/ silver plating	46.48%	7.4	Cu	7440-50-8	44.87%	7.14	448,662
				Fe	7439-89-6	1.07%	0.17	10,682
				Zn	7440-66-6	0.08%	0.012	754
				Ag	7440-22-4	0.47%	0.075	4,713
die attach	silver epoxy	0.69%	0.11	Ag	7440-22-4	0.55%	0.088	5,530
				epoxy resin	Proprietary	0.14%	0.022	1,382
encapsulation*	EMC GREEN	43.9%	6.99	silica	7631-86-9	36.13%	5.75	361,317
				epoxy resin	29690-82-2	3.2%	0.51	32,047
				phenol resin	9003-35-4	2.26%	0.36	22,622
				carbon black	1333-86-4	0.08%	0.012	754
				metal hydroxide	1309-42-8	2.23%	0.355	22,307
plating	matte tin	3.46%	0.55	Sn	7440-31-5	3.46%	0.55	34,561

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)